

# N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}$ (m $\Omega$ )(Typ.)	I <sub>D</sub> (A) <sup>a, e</sup>	Q <sub>g</sub> (Typ.)		
100	33 at V <sub>GS</sub> = 10 V	- 28	37 nC		
100	35 at V <sub>GS</sub> = 4.5 V	20			

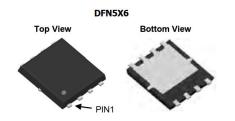
#### **FEATURES**

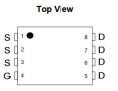
- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

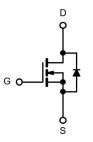


#### **APPLICATIONS**

- DC/DC Primary Side Switch
- Industrial







N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATING</b>	<b>S</b> ( $T_A = 25  ^{\circ}C$ , unle	ess otherwise n	oted)		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	100	V	
Gate-Source Voltage		V <sub>GS</sub>	V <sub>GS</sub> ± 20		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		28		
	T <sub>C</sub> = 100 °C	I <sub>D</sub>	19.5	A	
Pulsed Drain Current (t = 300 μs)		I <sub>DM</sub>	80		
Single Pulse Avalanche Energy	L = 0.5 mH	E <sub>AS</sub>	200	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		68	w	
	T <sub>C</sub> = 100 °C	$P_{D}$	27.2		
	T <sub>A</sub> = 25 °C	'	3.5 <sup>b, c</sup>		
	T <sub>A</sub> = 100 °C		1.4 <sup>b, c</sup>		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, f</sup>	t ≤ 10 s	R <sub>thJA</sub>	-	42	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R <sub>thJC</sub>	-	2.2	]	

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. The DFN5X6 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 65  $^{\circ}\text{C/W}.$



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	•			<u>'</u>			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	=	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1	-	3	] V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ	
	I <sub>DSS</sub>	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> =85°C	=	Ξ	10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	28	-	-	Α	
Drain-Source On-State Resistance <sup>a</sup>	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A	-	33	38		
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A	-	35	43	mΩ	
Forward Transconductance a	9 <sub>fs</sub>	$V_{DS} = 5 \text{ V}, I_D = 10 \text{ A}$	-	44	-	S	
Dynamic <sup>b</sup>	'		<u>'</u>	<b>'</b>			
Input Capacitance	C <sub>iss</sub>		-	2150	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{MHz}$	-	83	-0		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	61			
Total Gate Charge <sup>c</sup>	Qg		-	37	1-1		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	5.4	_	nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>		-	7.5			
Gate Resistance	$R_g$	f = 1 MHz	-	1	=	Ω	
Turn-On Delay Time °	t <sub>d(on)</sub>		-	28	-		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_q = 3 \Omega$	-	17	=	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D = 15 \text{ A}, V_{GEN} = 10 \text{ V},$	=	70	-		
Fall Time <sup>c</sup>	t <sub>f</sub>		8	11			
Drain-Source Body Diode Ratings a	nd Characteris	stics <sup>b</sup> (T <sub>C</sub> = 25 °C)	*	<del>!</del>		in .	
Continuous Source Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	28	Α	
Pulsed Source Current	I <sub>SM</sub>		-	-	80	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0 V	-	-	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 10 A di/dt = 100 A/vo	-	39	-	ns	
Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	-	45	-	nC	

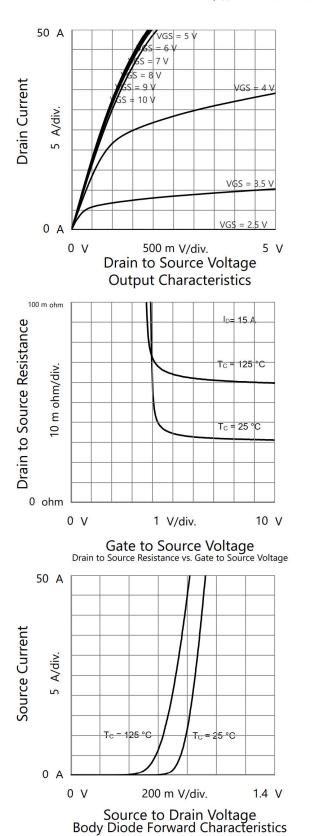
### Notes

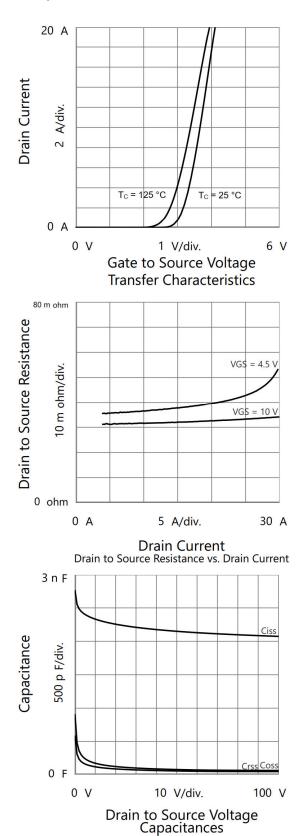
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



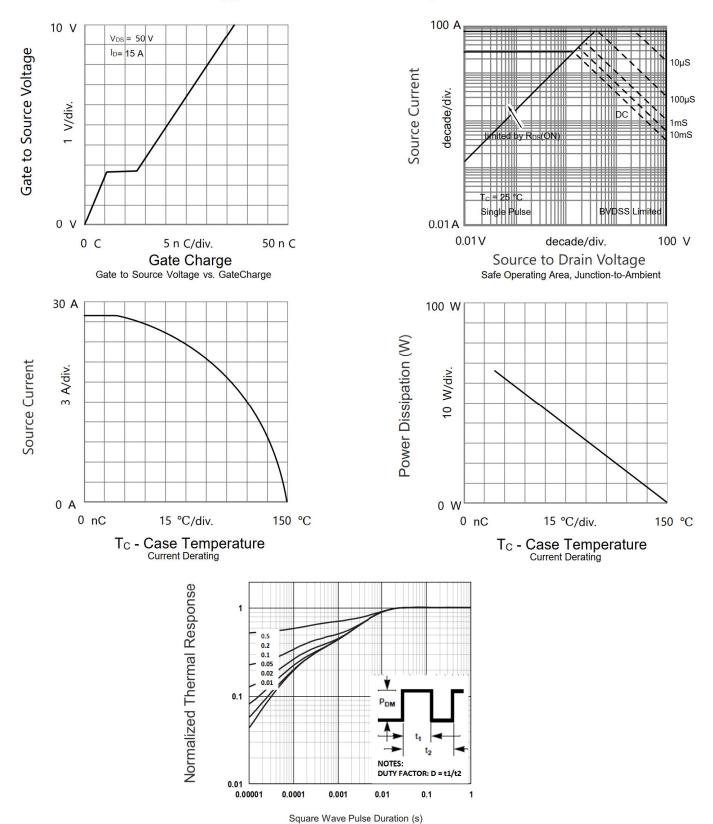
### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)







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Normalized Thermal Transient Impedance, Junction-to-Ambient





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